



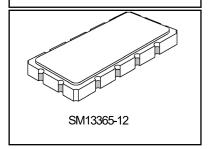
SF2267A

- Precision SAW IF Filter
- Hermetic 13.3 x 6.5 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage on any Non-ground Terminal	10	VDC
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

70 MHz SAW Filter



Electrical Characteristics

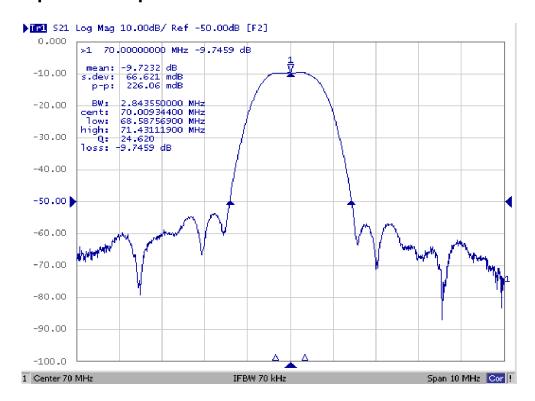
Characteristic	Sym	Notes	Min	Тур	Max	Units
Center Frequency	f _C		69.9	70.0	70.1	MHz
Insertion Loss	IL			9.8	12.0	dB
1 dB Bandwidth	BW ₁			1.00		
3 dB Bandwidth	BW ₃		1.26	1.32		MHz
40 dB Bandwidth	BW ₄₀			2.84	2.90	1
Amplitude Ripple, f _C ± 0.35 MHz				0.3	1.0	dB _{P-P}
Group Delay Ripple, f _C ± 0.35 MHz				160	280	ns _{P-P}
Relative Attenuation:						
DC to 65 MHz			45	55		dB
75 to 200 MHz			45	55		
Operating Temperature Range			-40		+80	°C

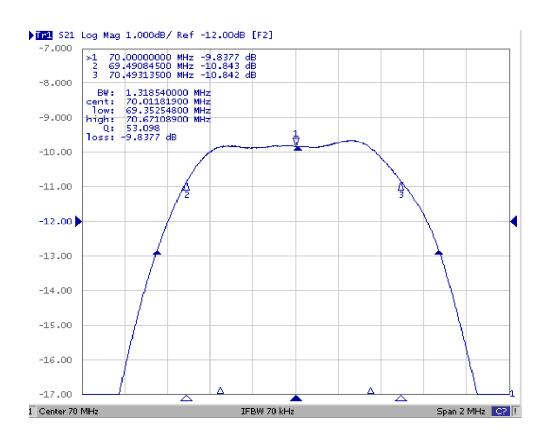
Impedance Matching to 50 Ω Unbalanced Source/Load	External L-C
Case Style	13.3 x 6.5 mm Nominal Footprint

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling. NOTES:

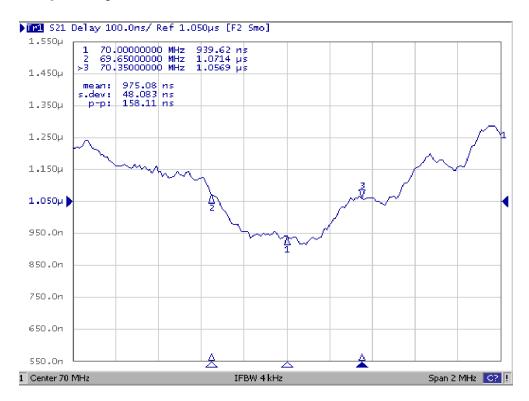
- 1. The design, manufacturing process, and specifications of this device are subject to change.
- 2. US or International patents may apply.
- 3. RoHS compliant from the first date of manufacture.

Filter Amplitude Response Plots

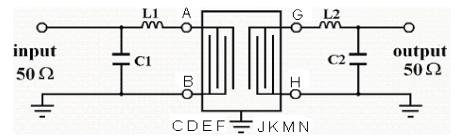




Filter Group Delay Plot

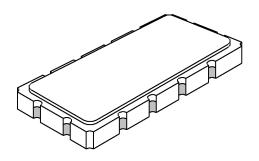


Tuning Component Values



L1 = 470 + 47 nH, C1 = 100 pF, L2 = 560 nH, C2 = 100 pF

Ceramic Surface-mount 12-Terminal Case 13.3 x 6.5 mm Nominal Footprint



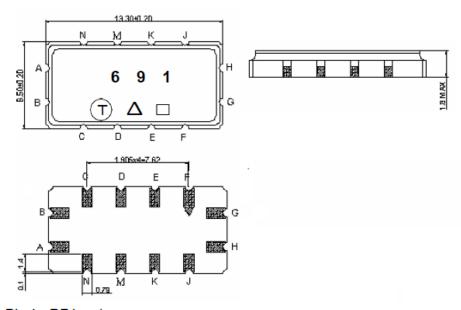
Case Material

Materials				
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel			
Lid Plating	2.0 to 3.0 µm Nickel			
Body	Al ₂ O ₃ Ceramic			

Electrical Connections

Connection	Terminals
Input	A
Output	G
Case Ground	All others

Case Outline Drawing



Pin A -RF input

Pin B -RF input ground

Pin G -RF output

Pin H -RF output ground

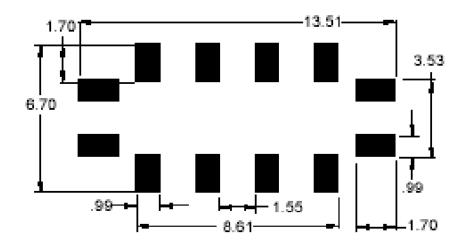
Pin C, D, E, F, J, K, M, N - Ground

□ : Week Code (Follow the table from planner each year)

Unit: mm

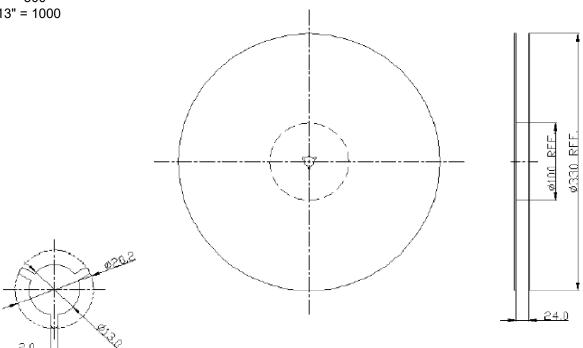
△ : Product / Year Code

PCB Pad Layout

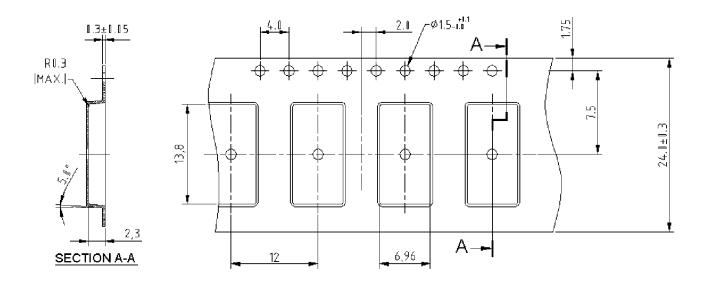


Tape and Reel Specifications





13.3X6.5



Recommended Reflow Profile

- 1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
- 2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
- 3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
- 4. Time: 5 times maximum.

